



SOT223-1

plastic small outline package; 4 leads; body width 3.5 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO4
Package type industry code	SO4
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	TO-261
Mounting method type	S (surface mount)
Issue date	19-2-2003

Table 1. Package summary

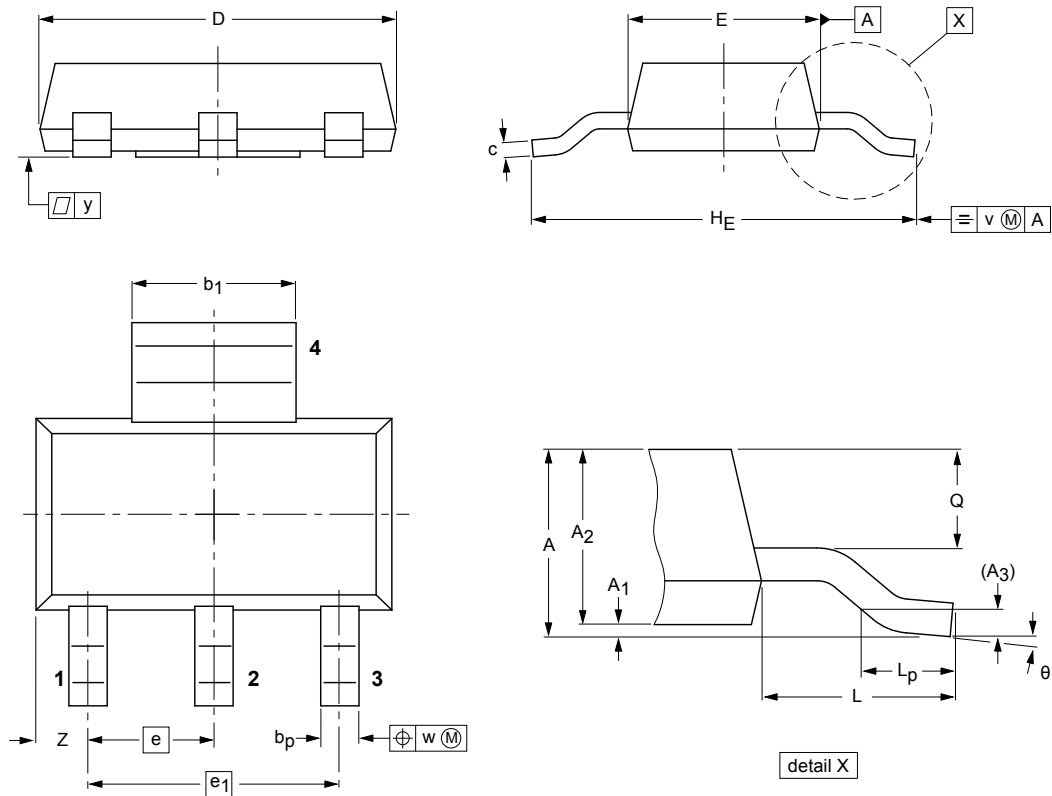
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.3	-	6.5	6.7	mm
E	package width	3.3	-	3.5	3.7	mm
A	seated height	[tbd]	-	1.7	1.8	mm
A ₂	package height	1.5	-	1.6	1.7	mm
n ₂	actual quantity of termination	-	-	4	-	



2. Package outline

SO4: plastic small outline package; 4 leads; body width 3.5 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	H _E	L	L _p	Q	v	w	y	Z	θ
mm	1.8	0.10 0.02	1.7 1.5	0.25	0.85 0.65	3.15 2.95	0.35 0.25	6.7 6.3	3.7 3.3	2.3	4.6	7.3 6.7	1.75	1.02 0.62	1.0 0.8	0.2	0.1	0.1	1.2 0.7	10° 0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT223-1		TO-261				99-12-15 03-02-19

Fig. 1. Package outline SO4 (SOT223-1)

3. Soldering

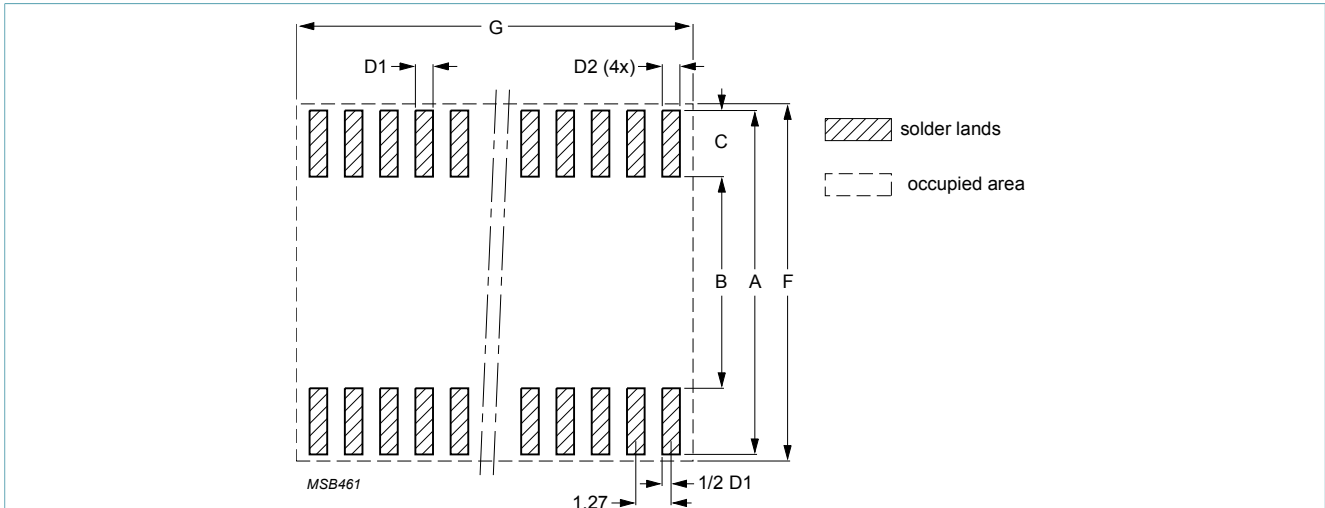


Fig. 2. Reflow soldering footprint for SO4 (SOT223-1)

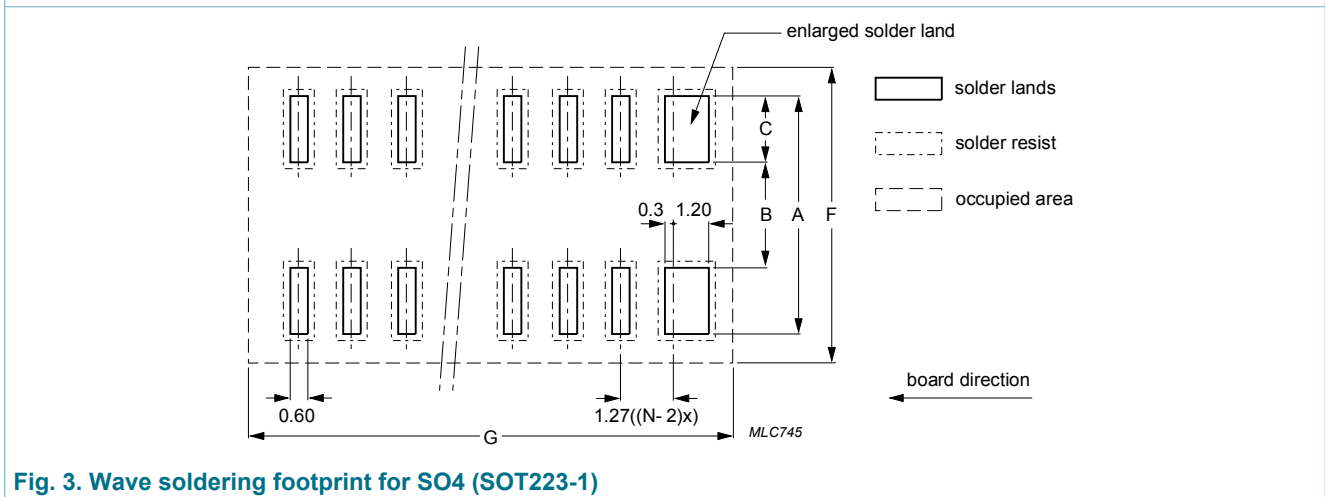


Fig. 3. Wave soldering footprint for SO4 (SOT223-1)

4. Legal information

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